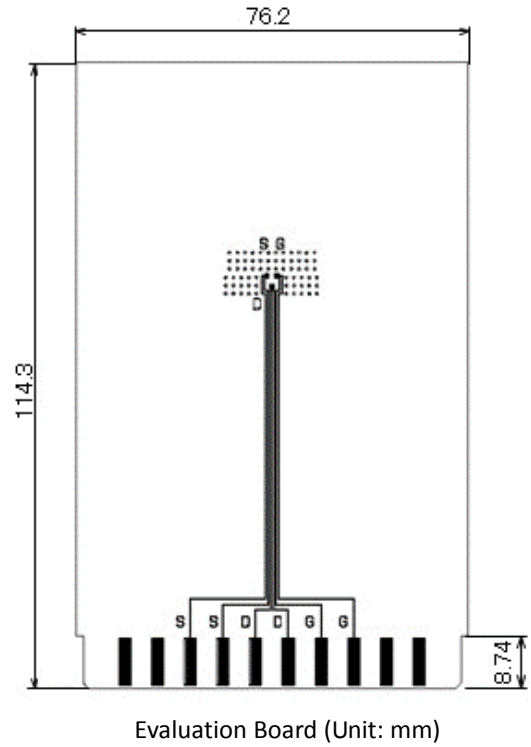


**●SOT-323-3A Power Dissipation (JESD51-7)**

Power dissipation data for the SOT-323-3A is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board : The board using 4 copper layer.  
 (76.2mm×114.3mm Area: about 8700mm<sup>2</sup>)
- 1st layer : No copper foil
- 2nd layer : 70mm×70mm\_Connected to heat-sink.
- 3th layer : 70mm×70mm\_Connected to heat-sink.
- 4th layer : No copper foil
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6mm
- Through-hole : φ0.2mm x 60pcs



2. Power Dissipation vs. Ambient temperature

Board Mount(Tjmax = 125°C)

AmbientTemperature(°C)	PowerDissipation Pd (mW)	θja(°C/W)
25	350	357.14
85	182	
150	0	

